

In the Specification:

Kindly make the following amendments to the specification:

Kindly amend the title to read:

~~SILICON SPRING ELECTRODE AND~~ METHOD FOR MANUFACTURING  
ANISOTROPIC CONDUCTIVE SHEET

Page 1, after the title and before numbered line 5,  
insert:

--This application claims the benefit of Japanese  
Application No. 2003-405851 filed December 4, 2003 and  
PCT/JP2004/017783 filed November 30, 2004, which are hereby  
incorporated by reference in their entirety.--

Kindly replace the paragraph beginning at page 1, numbered  
line 7 with the following rewritten paragraph:

The present invention relates to ~~a silicon spring electrode~~  
~~and~~ an anisotropic conductive sheet which employs ~~the~~ silicon  
spring ~~electrode~~ electrodes.

Kindly replace the paragraph beginning at page 3, numbered  
line 23 with the following rewritten paragraph:

The present invention is carried out in view of the above-  
mentioned problems in order to provide an anisotropic conductive  
sheet which can be applied to more finely and more narrowly  
pitched electrodes ~~arranged with a finer and narrower pitch for~~  
conductive test.

Kindly replace the paragraph beginning at page 3, numbered  
line 27 with the following rewritten paragraph:

In order to solve the above-mentioned problems ~~above,~~  
~~silicon spring electrodes by the present inventions are~~

~~constituted as specified in (1) to (3), and a method for manufacturing an anisotropic conductive sheets sheet~~ by the present invention ~~are~~ is constituted as specified in ~~(4) to (6)~~ (1).

(1) A method for manufacturing an anisotropic conductive sheet comprising: step A; etching through a monocrystal silicon wafer by a deep reactive ion etching so as to form a part having a bending leaf spring shape such that planes of the formed leaf spring are parallel to a cross section of the wafer, step B; forming a silicon spring electrode by forming a conductive layer on a surface of the part having the bending leaf spring shape formed in step A, and step C; inserting a plurality of the silicon spring electrodes formed in step B respectively into through holes of a soft plastic sheet such that the spring electrodes are clamped and fixed to the soft plastic sheet.